IN THE SPECIFICATION:

Please amend the paragraph beginning at line 23 of page 3 of the Substitute Specification and ending on line 12 of page 4 to read as follows:

Inventively, a method for producing an integrated semiconductor component is also offered and has the following steps:

preparing a semiconductor substrate having at least one first region and at least one second region;

producing gate paths in the first and the second regions of the semiconductor substrate;

producing source/drain regions neighboring the gate paths as well as at least two spaces spacers at the gate paths in the first region of the semiconductor substrate;

producing source/drain regions neighboring the gate paths in the second region of the semiconductor substrate; and

preparing contacts to predetermined source/drain regions before all spacers in the first region of the semiconductor substrate have been produced.